

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/14/2022

Details for "OPA2210IDGKR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2210IDGKR	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGK 8	3x3x1	27.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000005	0.006947	69	0.000018	0
Precious Metals	Gold	7440-57-5	0.071966	99.993053	999931	0.258346	2583
Sub-Total			0.071971	100	1000000	0.258364	2584
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.2732	81.999934	819999	0.980742	9807
Thermoplastics	Epoxy	85954-11-6	0.059971	18.000066	180001	0.215286	2153
Sub-Total			0.333171	100	1000000	1.196028	11960
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	12.163924	96.157502	961575	43.666454	436665
Magnesium and Its Alloys	Magnesium	7439-95-4	0.021758	0.172	1720	0.078108	781
Nickel and Its Alloys	Nickel	7440-02-0	0.371467	2.936498	29365	1.333504	13335
Other inorganic Materials	Silicon	7440-21-3	0.090131	0.712498	7125	0.323555	3236
Precious Metals	Silver	7440-22-4	0.00272	0.021502	215	0.009764	98
Sub-Total			12.65	100	1000000	45.411386	454114
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.509852	97.3	973000	1.830283	18303
Precious Metals	Gold	7440-57-5	0.001572	0.3	3000	0.005643	56
Precious Metals	Palladium	7440-05-3	0.011004	2.1	21000	0.039503	395
Precious Metals	Silver	7440-22-4	0.001572	0.3	3000	0.005643	56
Sub-Total			0.524	100	1000000	1.881072	18811
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	11.708588	87.700003	877000	42.031874	420319
Other Plastics and Rubber	Carbon Black	1333-86-4	0.040052	0.299999	3000	0.14378	1438
Thermoplastics	Epoxy	85954-11-6	1.602087	11.999998	120000	5.751225	57512
Sub-Total			13.350727	100	1000000	47.926879	479269
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.926581	100	1000000	3.326271	33263
Sub-Total			0.926581	100	1000000	3.326271	33263
Total			27.85645			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic assemblies.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.